Silicon N-Channel MOS FET

HITACHI

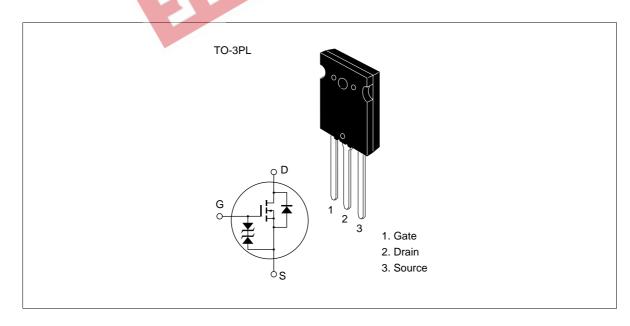
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Tom.cn Suitable for switching regulator and DC-DC converter

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item		Symbol	Ratings	Unit				
Drain to source voltage	2SK1628	V _{DSS}	450	V				
	2SK1629		500					
Gate to source voltage		V_{GSS}	±30	V				
Drain current	I _D	30	А					
Drain peak current	I _{D(pulse)} *1	120	А					
Body to drain diode reverse	I _{DR}	30	А					
Channel dissipation	Pch*2	200	W					
Channel temperature	Tch	150	°C					
Storage temperature		Tstg	-55 to +150	°C				
Note 1. $PW \le 10 \mu s$, duty cycle $\le 1\%$ 2. Value at $T_c = 25^{\circ}C$								

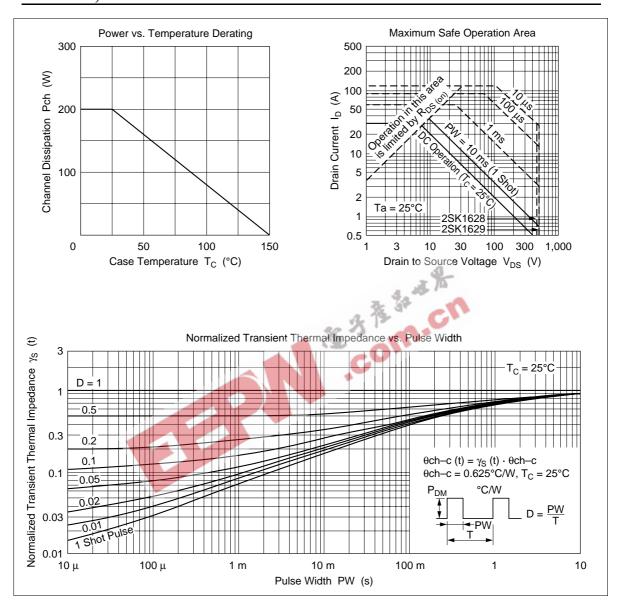


Electrical Characteristics (Ta = 25°C)

Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1628	$V_{(BR)DSS}$	450	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
breakdown voltage	2SK1629	-	500	=			
Gate to source breakdown voltage		$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current		I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage	2SK1628	I _{DSS}	_	_	250	μΑ	$V_{DS} = 360 \text{ V}, V_{GS} = 0$
drain current	2SK1629	-					$V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source cutoff	voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static Drain to source	2SK1628	R _{DS(on)}	_	0.20	0.25	Ω	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
on state resistance	2SK1629	-	_	0.22	0.27	3	
Forward transfer adm	ittance	yfs	12	20	_	S	$I_D = 15 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance		Ciss	_	2800	一卷	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance		Coss	_	780	3"	pF	f = 1 MHz
Reverse transfer capa	acitance	Crss	- \	90	7.0	pF	-
Turn-on delay time		t _{d(on)}	+	32		ns	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time		tr	-) /	140	_	ns	$R_L = 2 \Omega$
Turn-off delay time		t _{d(off)}		200	_	ns	-
Fall time	1	t _f	_	100	_	ns	-
Body to drain diode for voltage	orward	V _{DF}	_	1.1	_	V	$I_F = 30 \text{ A}, V_{GS} = 0$
Body to drain diode re recovery time	everse	t _{rr}	_	600	_	ns	$I_F = 30 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note 1. Pulse test

See characteristics curves of 2SK1169, 2SK1170

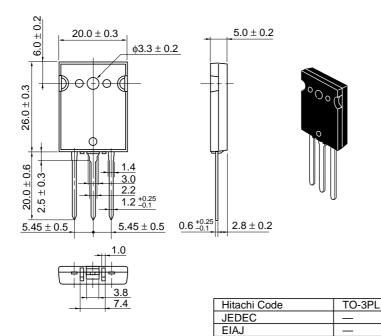




Unit: mm

9.9 g

Weight (reference value)



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